

IN THE SPECIFICATION

At page 1, line 2 of the specification of the present application, please insert the following paragraph at the top of the page prior to the first heading:

The present application claims priority from and is a divisional application of U.S. Patent Application No. 09/859,842 filed May 16, 2001, which is owned by the same assignee as the present patent application.

Please add the following new paragraph after the paragraph ending on line 7 of page 5:

Figure 10C illustrates another embodiment of a spring pin implemented as a micromachined bump connector.

Please amend the paragraph beginning at page 5, line 8, as follows:

Figure 10CD illustrates one embodiment of a spring pin implemented as a liquid-based system.

Please amend the paragraph beginning at page 19, starting at line 19, as follows:

Figure 10B illustrates one embodiment of a spring pin implemented as a micromachined bump connector. The spring pin 1030 is moved by electrostatic force, to couple the conductive layer 1030 to the device under test. In this system, either the pin may be rigid, and a conductor may be coupled to the pin, or the pin may itself move, and be physically coupled to and decoupled from the device. The alternative embodiment of Fig. 10C shows the pin 1035 being rigid, while a flexible coupling mechanism 1045 moves up and down, to electrically couple the pin 1035 to the device under test.

Please amend the paragraph beginning at page 20, line 3, as follows:

Figure 10C-10D illustrates one embodiment of a spring pin implemented as a liquid-based system. The pin 1050 is rigid, and has a counterpart 1055. The area between the pin 1050 and its counterpart 1055 is bridged by a material 1060 which may be made to expand to cause an electrical connection. Thus, for example, a liquid may be used, which is expanded by micromachined relays, to establish a connection. Alternative materials may be used if they are responsive to a signal to expand and contract.

Please amend the paragraph beginning at page 20, line 10, as follows:

The implementations of spring pins for use with micromachine relays discussed in Figure 10A-C Figures 10A-D are merely exemplary. It is to be understood that

alternative methods of establishing an electrical connection between a device under test and a pin electronics circuit may be used.